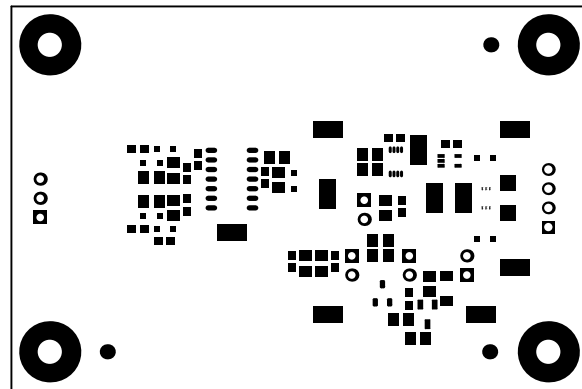
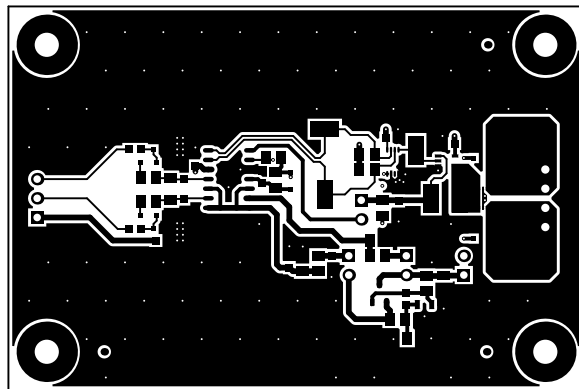


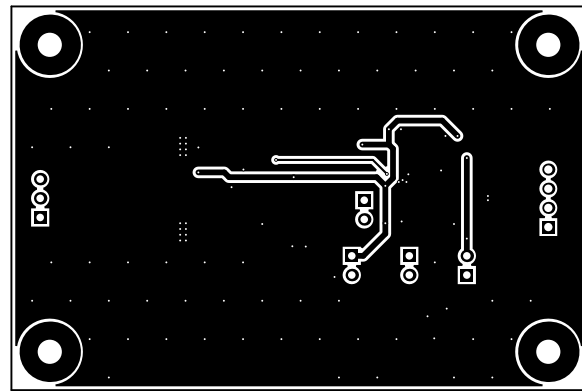
| | | | |
|----------------------------------|------------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EUM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: TIDA-01065 | | |
| PLOT NAME = Top Overlay | GENERATED : 8/25/2016 | 7:03:11 PM | TEXAS INSTRUMENTS |



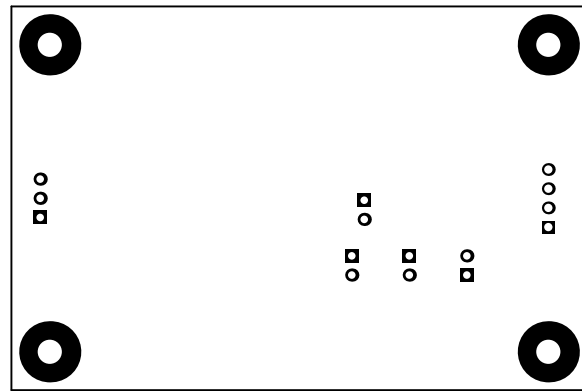
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EVM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: TIDA-01065 | | |
| PLOT NAME = Top Solder Mask | GENERATED : 8/25/2016 7:03:12 PM | TEXAS INSTRUMENTS | |



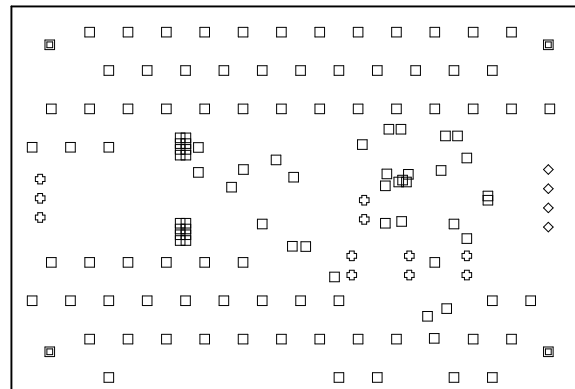
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EVM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = Layer 1 - Top Layer | TID #: TIDA-01065 | | |
| PLOT NAME = Top Layer | GENERATED : 8/25/2016 7:03:13 PM | TEXAS INSTRUMENTS | |



| | | | |
|-------------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EVM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = Layer 2 - Bottom Layer | TID #: TIDA-01065 | | |
| PLOT NAME = Bottom Layer | GENERATED : 8/25/2016 7:03:13 PM | TEXAS INSTRUMENTS | |

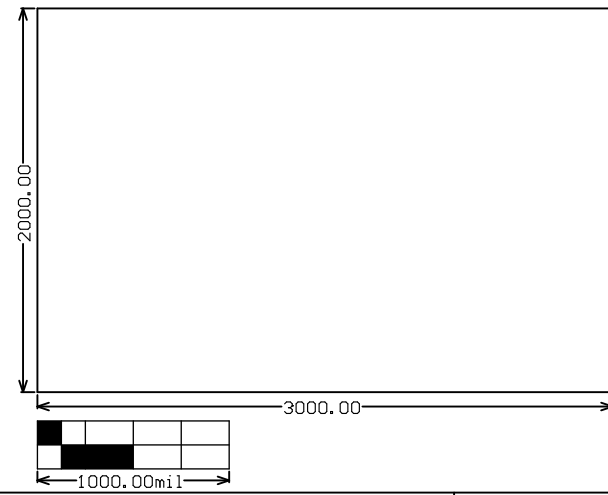


| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EVM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: TIDA-01065 | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 8/25/2016 7:03:14 PM | TEXAS INSTRUMENTS | |



| Symbol | Quantity | Finished Hole Size | Plated | Hole Type |
|-----------|----------|---------------------|--------|-----------|
| □ | 122 | 10.00mil (0.254mm) | PTH | Round |
| ⊕ | 11 | 39.37mil (1.000mm) | PTH | Round |
| ◇ | 4 | 43.31mil (1.100mm) | PTH | Round |
| ■ | 4 | 125.98mil (3.200mm) | PTH | Round |
| 141 Total | | | | |

| | | | |
|----------------------------------|------------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EUM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: TIDA-01065 | | |
| PLOT NAME = Drill Drawing | GENERATED : 8/25/2016 | 7:03:15 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|------------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: ISA-EVM-01065 | REV: Rev A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: TIDA-01065 | | |
| PLOT NAME = Board Dimensions | GENERATED : 8/25/2016 | 7:03:16 PM | TEXAS INSTRUMENTS |

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